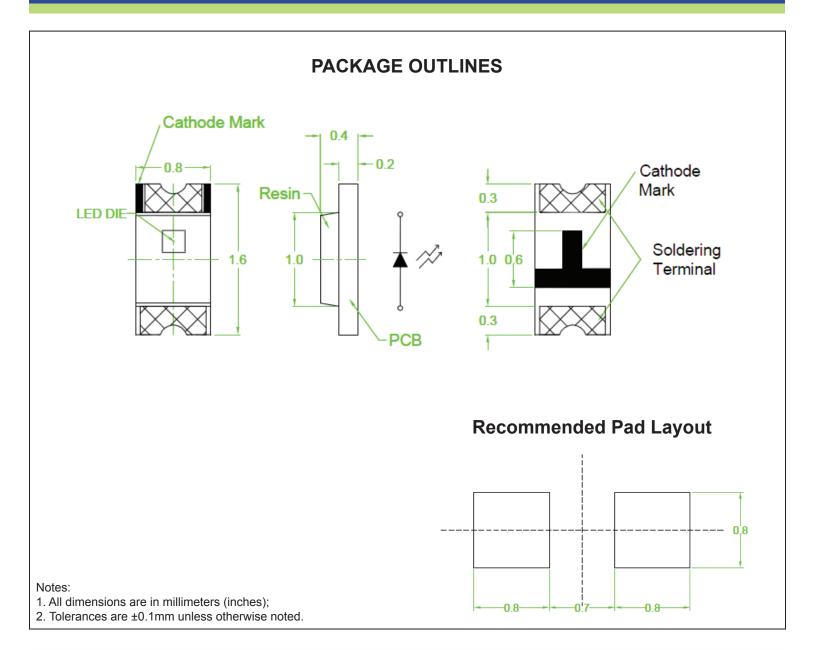


SPECIFICATIONS CS63CGT1C



Part Number	Chip Material	Color of Emission	Lens Type	
CS63CGT1C	InGaN/GaN	Green	Water Clear	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Value	Unit	
Forward current	If	20	mA	
Reverse current @5V	lr	50	μA	
Power dissipation	Pd	80	mW	
Peak forward current (1/10 @ 10kHz)	lfp	100	mA	
Electrostatic Discharge	ESD	150	V	
Operating temperature range	Topr	-40~+85	°C	
Storage temperature range	Tstg	-40~+90	°C	
Soldering Temperature	Tsol	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

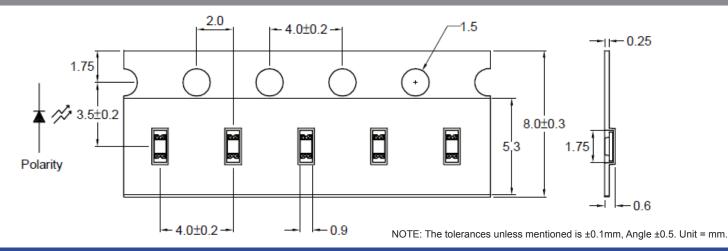
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Spectral half bandwidth	Δλ	I _F = 20mA		36		nm
Peak Wavelength	λР	I _F = 20mA		518		nm
Dominant wavelength	λD	I _F = 20mA		525		nm
Forward Voltage	Vf	I _F = 20mA		3.5	4.0	V
Luminous intensity	lv	I _F = 20mA	200	500	800	mcd
Viewing angle at 50% lv	20 1/2	I _F = 20mA	1	140		Deg

^{*}NOTE: 1. The forward voltage data did not including ±0.1V tolerance 2. The luminous intensity data did not including ±15% tolerance

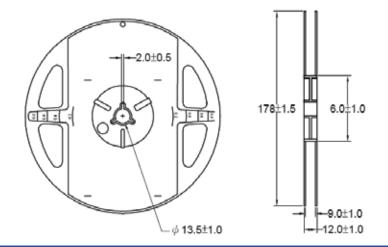




DIMENSIONS OF TAPE (Unit: mm)



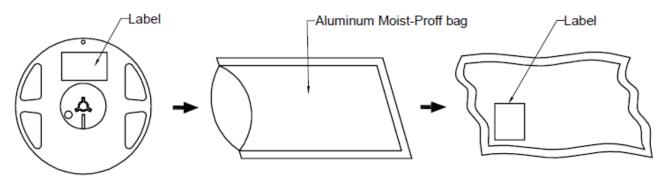
REEL DIMENSIONS



NOTES:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 4,000pcs/Reel

PACKAGING SPECIFICATION



RoHS Compliant



OPTICAL CHARACTERISTIC CURVES

Fig.1 Forward current vs. Forward Voltage

1000
100
1.0
0.1
1.0
2.0
3.0
4.0
5.0

Forward Voltage(V)

Relative Intensity

Fig.2 Relative Intensity vs. Forward Current

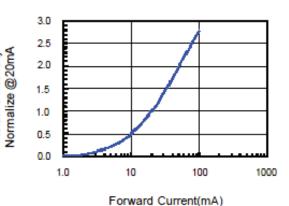


Fig.3 Forward Voltage vs. Temperature

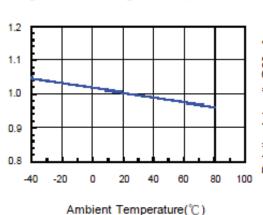


Fig.4 Relative Intensity vs. Temperature

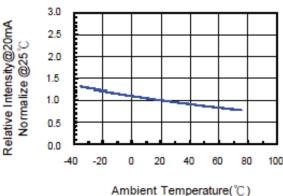


Fig.5 Relative Intensity vs. Wavelength

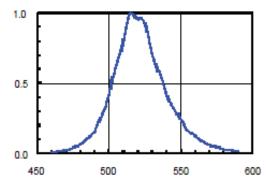
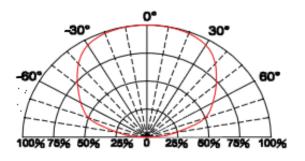


Fig.6 Directive Radiation

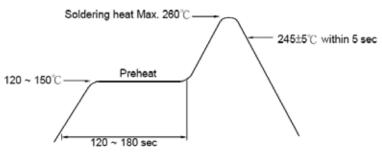




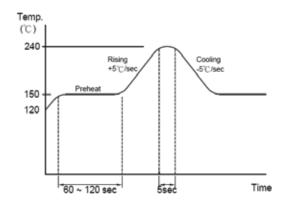


SOLDERING CONDITIONS – LAMP TYPE LED

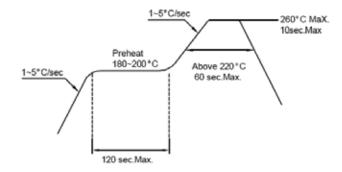
- 1. Hand Solder
 Basic spec is ≤ 280°C 3 sec one time only.
- 2. Wave Solder



3-1. LEAD Reflow Solder



3-2. PB-Free Reflow Solder



Notes:

- 1. Reflow soldering should not be done more than two times.
- 2. When soldering, do not put stress on the LEDs during heating.
- 3. After soldering, do not warp the circuit board.

